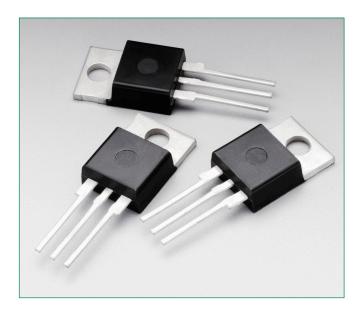


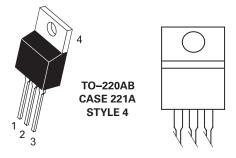
Surface Mount -400V - 800V > MAC212A8, MAC212A10

# MAC212A8, MAC212A10





# Pin Out



## **Description**

Designed primarily for full-wave AC control applications, such as light dimmers, motor controls, heating controls and power supplies; or wherever full-wave silicon gate controlled solid-state devices are needed. Triac type thyristors switch from a blocking to a conducting state for either polarity of applied main terminal voltage with positive or negative gate triggering.

#### **Features**

- Blocking Voltage to 800 Volts
- All Diffused and Glass Passivated Junctions for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Gate Triggering Guaranteed in Four Modes (Quadrants)
- Pb-Free Packages are Available

### **Functional Diagram**



## **Additional Information**









# **Maximum Ratings** $(T_J = 25^{\circ}C \text{ unless otherwise noted})$

Rating	Symbol	Value	Unit	
Peak Repetitive Off-State Voltage (Note 1)	MAC212A8	V <sub>DRM</sub> ,	600	V
(– 40 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open)	MAC212A10	V <sub>RRM</sub>	800	v
On-State RMS Current (Full Cycle Sine Wave, 50 to 60 Hz, T <sub>c</sub>	= +85°C)	I <sub>T (RMS)</sub>	12	А
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave $T_c = +25^{\circ}\text{C}$ ) Preceded and followed by rated current	, 60 Hz,	I <sub>TSM</sub>	100	А
Circuit Fusing Considerations (t = 8.3 ms)	l²t	40	A²sec	
Peak Gate Power ( $T_c = +85^{\circ}\text{C}$ , Pulse Width = 10 $\mu$ s)	$P_{GM}$	20	W	
Average Gate Power (t = 8.3 ms, $T_c = +85$ °C)	P <sub>G (AV)</sub>	0.35	W	
Peak Gate Current ( $T_c = +85$ °C, Pulse Width = 10 $\mu$ s)	I <sub>GM</sub>	2.0	А	
Operating Junction Temperature Range	$T_{J}$	-40 to +125	°C	
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

## **Thermal Characteristics**

Rating		Symbol	Value	Unit
Thermal Resistance,	Junction-to-Case (AC) Junction-to-Ambient	R <sub>8JC</sub>	2.0 62.5	°C/W
Maximum Lead Temperature for Solde 10 seconds	ring Purposes, 1/8" from case for	T <sub>L</sub>	260	°C

V<sub>DRM</sub> and V<sub>BRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

# **Thyristors**

# **Electrical Characteristics - OFF** $(T_1 = 25^{\circ}\text{C unless otherwise noted}; \text{Electricals apply in both directions})$

Characteristic		Symbol	Min	Тур	Max	Unit
Peak Repetitive Blocking Current	T <sub>J</sub> = 25°C	l <sub>DRM</sub> ,	-	-	10	μА
$(V_D = V_{DRM} = V_{RRM}; Gate Open)$	T <sub>J</sub> = +125°C	I <sub>RRM</sub>	-	-	2.0	mA

## **Electrical Characteristics** · **ON** $(T_J = 25^{\circ}\text{C unless otherwise noted; Electricals apply in both directions)$

Characteristic			Min	Тур	Max	Unit
Peak On-State Voltage (TM = 14 A Peak; Pulse Width = 1 to 2 ms, Duty Cycle 2%)			-	1.3	1.75	V
	MT2(+), G(+)		-	12	50	
Gate Trigger Current (Continuous dc)	MT2(+), G(-)		-	12	50	mA
(Main Terminal Voltage = 12 Vdc, $R_L = 100 \Omega$ )	MT2(-), G(-)	GT	_	20	50	mA
	MT2(-), G(+)		-	35	75	
	MT2(+), G(+)		-	0.9	2.0	
Gate Trigger Voltage (Continuous dc)	MT2(+), G(-)	V <sub>GT</sub>	-	0.9	2.0	V
(Main Terminal Voltage = 12 Vdc, $R_L = 100 \Omega$ )	MT2(-), G(-)		-	1.1	2.0	V
	MT2(-), G(+)		-	1.4	2.5	
Gate Non–Trigger Voltage (Continuous dc) (Main Terminal Voltage = 12 Vdc, $R_L$ = 100 $\Omega$ ) All Four Quadrants			0.02	-	-	V
Holding Current (Main Terminal Voltage = 12 Vdc, Gate Open, Initiating Current = $\pm$ 200 mA)		I <sub>H</sub>	-	6.0	50	mA
Turn-On Time (Rated $V_{DRM'}$ $I_{TM} = 17$ A) ( $I_{GT} = 120$ mA, Rise Time = 0.1 µs, Pulse Width = 2 µs)		t <sub>gt</sub>	-	1.5	_	μѕ

## **Dynamic Characteristics**

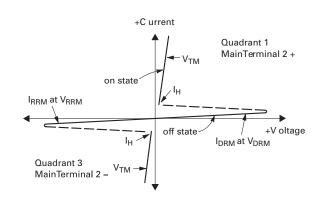
Characteristic	Symbol	Min	Тур	Max	Unit
Critical Rate of Rise of Commutation Voltage ( $V_D$ = Rated $V_{DRM'}$ $I_{TM}$ = 17 A, Commutating di/dt = 6.1 A/ms, Gate Unenergized, $T_C$ = +85°C)	di/dt <sub>(C)</sub>	_	5.0	_	V/µs
Critical Rate of Rise of Off-State Voltage $(V_D = Rated V_{DRM}, Exponential Voltage Rise, Gate Open, T_C = +85°C)$	dv/dt	_	100	-	

# Surface Mount -400V - 800V > MAC212A8, MAC212A10

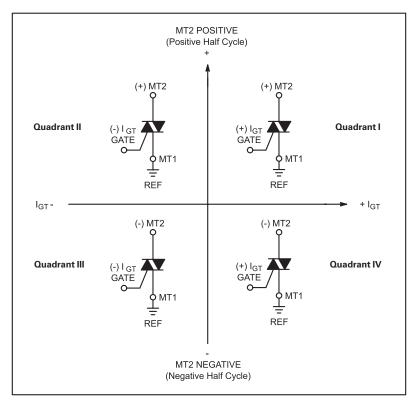
## **Voltage Current Characteristic of SCR**

Symbol	Parameter
$V_{DRM}$	Peak Repetitive Forward Off State Voltage
I <sub>DRM</sub>	Peak Forward Blocking Current
V <sub>RRM</sub>	Peak Repetitive Reverse Off State Voltage
I <sub>RRM</sub>	Peak Reverse Blocking Current
V <sub>TM</sub>	Maximum On State Voltage
I <sub>H</sub>	Holding Current

**Thyristors** 



## **Quadrant Definitions for a Triac**



All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used.





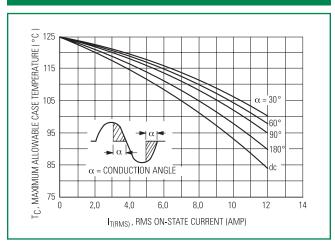


Figure 3. Maximum On-State Characteristics

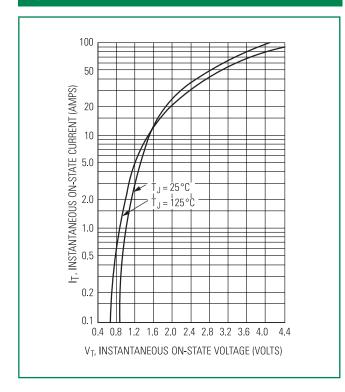


Figure 2. Power Dissipation

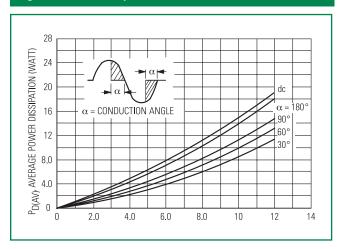


Figure 4. Maximum Non-Repetitive Surge Current

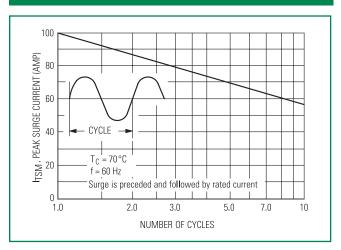
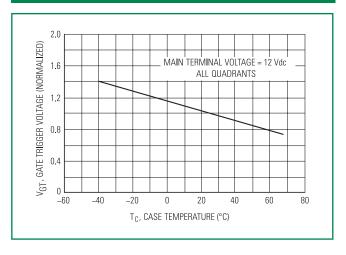
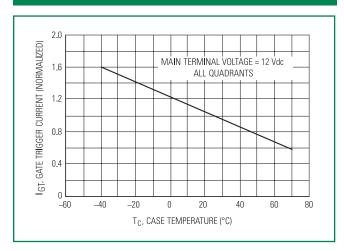


Figure 5. Typical Gate Trigger Voltage



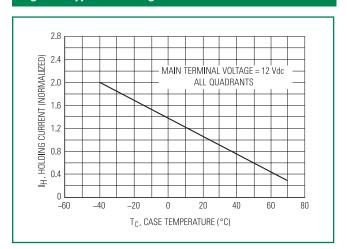


# Figure 6. Typical Gate Trigger Current

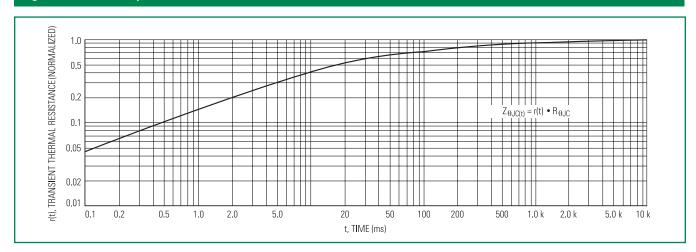


**Thyristors** 

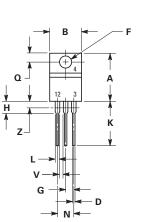
## **Figure 7. Typical Holding Current**

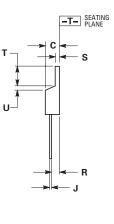


## Figure 8. Thermal Response



#### **Dimensions**

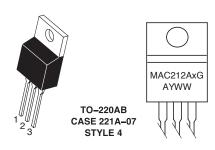




	Inches		Millim	neters
Dim	Min	Max	Min	Max
А	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.022	0.36	0.55
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

## **Part Marking System**



x= 8 or 10 A= Assembly Location Y= Year WW = Work Week

= Pb-Free Package

Pin Assignment						
1	Main Terminal 1					
2	Main Terminal 2					
3	Gate					
4	Main Terminal 2					

## **Ordering Information**

Device	Package	Shipping
MAC212A8	TO-220AB	
MAC212A8G	TO-220AB (Pb-Free)	500
MAC212A10	TO-220AB	Units/ Box
MAC212A10G	TO-220AB (Pb-Free)	

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